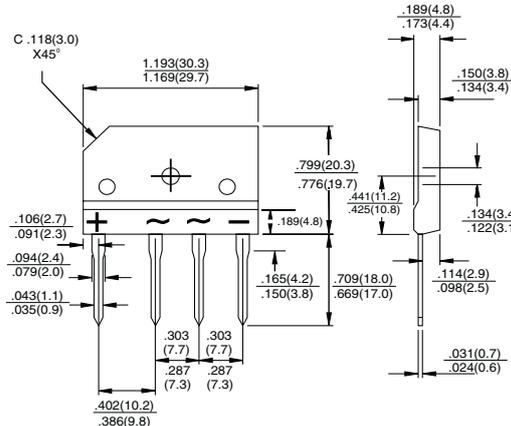


15 Amp. Glass Passivated Bridge

<p style="text-align: center;">Plastic Case</p>  <ul style="list-style-type: none"> • Mounting Instructions • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm. 	<p style="text-align: center;">Voltage 400 to 1000</p> <p style="text-align: center;">Current 15 A.</p> <div style="text-align: center; margin: 20px 0;">  </div> <ul style="list-style-type: none"> • Glass Passivated Junction Chips. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • High surge current capability. • The plastic material carries U/L recognition 94 V-O.
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Maximum Ratings, according to IEC publication No. 134

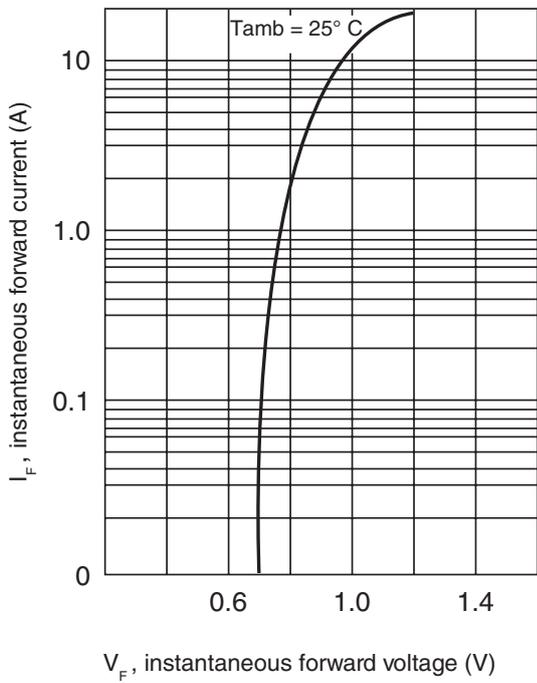
		D15XBV 40	D15XBV 60	D15XBV 80	D15XBV 100
V_{RRM}	Peak recurrent reverse voltage (V)	400	600	800	1000
V_{RMS}	Maximum RMS voltage (V)	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	15.0 A at $T_c: 107\text{ °C}$ 3.5 A at 25 °C			
I_{FSM}	10 ms. peak forward surge current (Jedec Method)	200 A			
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	2000 V			
I^2t	Current squared time (rating for fusing) (1ms.<t<10ms. $T_c = 25\text{ °C}$)	200 A ² sec			
T_j	Operating temperature range	– 55 to + 150 °C			
T_{stg}	Storage temperature range	– 55 to +150 °C			

Electrical Characteristics at $T_{amb} = 25\text{ °C}$

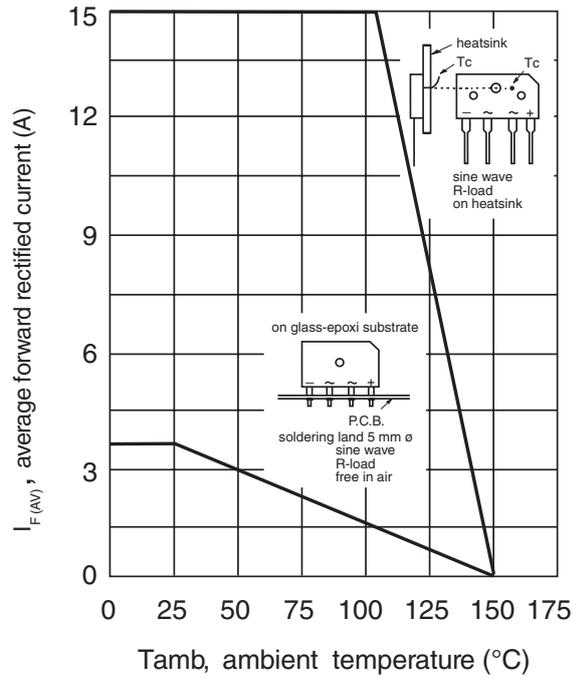
V_F	Max. forward voltage drop per diode at $I_F = 7.5\text{ A}$ $I_F = 15.0\text{ A}$	0.92V 1.07V
I_R	Max. instantaneous reverse current at V_{RRM}	10 μA
MAXIMUM THERMAL RESISTANCE		
$R_{th(j-c)}$	Junction-Case. With Heatsink.	1.5 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	22 °C/W

Rating And Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

